

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Original) A circuit device comprising:  
conductive patterns formed on a front surface of a circuit substrate; and  
circuit elements electrically connected respectively to the conductive patterns,  
wherein the conductive patterns include a first conductive pattern and a second  
conductive pattern formed more thickly than the first conductive pattern, and  
front surfaces of the first and second conductive patterns are placed at  
substantially equal levels, and a protruding portion is provided on a back surface of the second  
conductive pattern, the protruding portion protruding, in a thickness direction, from a back  
surface of the first conductive pattern.
2. (Original) A circuit device comprising:  
conductive patterns formed on a front surface of a circuit substrate; and  
circuit elements electrically connected to the conductive patterns,  
wherein the conductive patterns include a first conductive pattern and a second  
conductive pattern formed more thickly than the first conductive pattern, and  
back surfaces of the first and second conductive patterns are placed at  
substantially equal levels, and a protruding portion is provided on a front surface of the second  
conductive pattern, the protruding portion protruding, in a thickness direction, from a front  
surface of the first conductive pattern.
3. (Original) A circuit device comprising:  
conductive patterns formed on a front surface of a circuit substrate; and

circuit elements electrically connected to the conductive patterns,  
wherein the conductive patterns include a first conductive pattern and a second  
conductive pattern formed more thickly than the first conductive pattern, and  
protruding portions are provided respectively on a front surface and a back  
surface of the second conductive pattern, the protruding portions protruding in a thickness  
direction.

4. (Original) The circuit device according to any one of claims 1 to 3, wherein an  
edge portion having a thickness substantially equal to that of the first conductive pattern is  
formed around the protruding portion.

5. (Original) The circuit device according to claim 4, wherein a width of the edge  
portion is larger than the thickness of the first conductive pattern.

6. (Original) The circuit device according to any one of claims 1 and 3, wherein  
the protruding portion is buried in an insulating layer formed on the front surface of the circuit  
substrate.

7. (Currently amended) The circuit device according to any one of claims 1 or to  
3, wherein the circuit substrate is any one of a metal substrate, a ceramic substrate, a printed  
board, and a flexible sheet.

8. (Currently amended) The circuit device according to any one of claims 1 or to  
3, wherein a first circuit element is connected to the first conductive pattern, and  
a second circuit element having a current-carrying capacitance larger than the first  
circuit element is connected to the second conductive pattern.

9. (Original) A method of manufacturing a circuit device, comprising the steps of:

preparing a conductive foil having a protruding portion provided on a front surface thereof, the protruding portion protruding in a thickness direction;

bringing the conductive foil into intimate contact with a circuit substrate so as to bury the protruding portion in an insulating layer provided on a front surface of the circuit substrate; and

forming a first conductive pattern and a second conductive pattern which includes the protruding portion and which is thicker than the first conductive pattern, by partially removing the conductive foil in a region where the protruding portion is not provided.

10. (Original) A method of manufacturing a circuit device, comprising the steps of:

preparing a conductive foil having a protruding portion provided on a front surface thereof, the protruding portion protruding in a thickness direction;

bringing a back surface of the conductive foil into intimate contact with an insulating layer provided on a front surface of a circuit substrate; and

forming a first conductive pattern and a second conductive pattern which includes the protruding portion and which is thicker than the first conductive pattern, by partially removing the conductive foil in a region where the protruding portion is not provided.

11. (Original) A method of manufacturing a circuit device, comprising the steps of:

preparing a conductive foil having protruding portions provided on a front surface and a back surface thereof, the protruding portions protruding in a thickness direction;

bringing the conductive foil into intimate contact with a circuit substrate so as to bury the protruding portion in an insulating layer provided on a front surface of the circuit substrate; and

forming a first conductive pattern and a second conductive pattern which includes the protruding portions and which is thicker than the first conductive pattern, by partially removing the conductive foil in a region where the protruding portions are not provided.

12. (Original) The method according to any one of claims 9 to 11, wherein side surfaces of the protruding portion are curved surfaces.

13. (Original) The method according to any one of claims 9 to 11, wherein the conductive foil is patterned so that an edge portion can remain around the protruding portion, the edge portion having a thickness equal to that of the first conductive pattern.

14. (Original) The method according to claim 13, wherein a width of the edge portion is made larger than the thickness of the first conductive pattern.

15. (Original) The method according to any one of claims 9 to 11, wherein the first and second conductive patterns are formed by etching processing.